

I r f u

cea

saclay

# Zero Suppressed Digital Chip sensor for EUDET-JRA1 beam telescope

**Marie GELIN**

*on behalf of IRFU – Saclay and IPHC - Strasbourg*

## OUTLINE

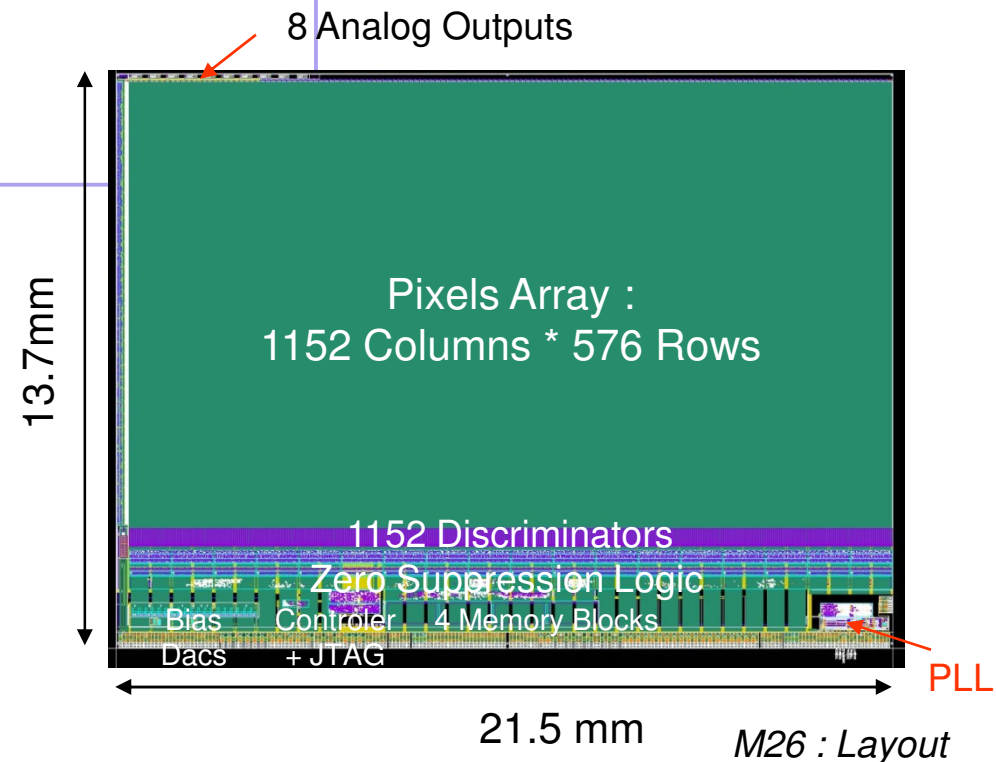
- Zero Suppressed Digital Chip (MIMOSA26) description
- MIMOSA26 characterization in-lab : summary
- MIMOSA26 characterization in beam (preliminary)
- Summary



# MIMOSA 26 : description

## Main parameters & Functionalities :

- **AMS-OPTO  $0.35\mu\text{m}$**
- **Pixel Size :  $18.4 \times 18.4 \mu\text{m}^2$**
- **Active Area :  $1152 \times 576$  pixels ( $21.2 \times 10.6 \text{ mm}^2$ )**
- **8 Analog test Outputs**
- **1152 end-column discriminators (663552 pixels)**
- **Slow Control Interface : JTAG**
- **Internal Bias (DACs)**
- **Zero suppression mode (SUZE-01)**



I r f u

cea

sac lay

**IPHC**  
Institut Pluridisciplinaire  
Hubert Curie en  
STRASBOURG



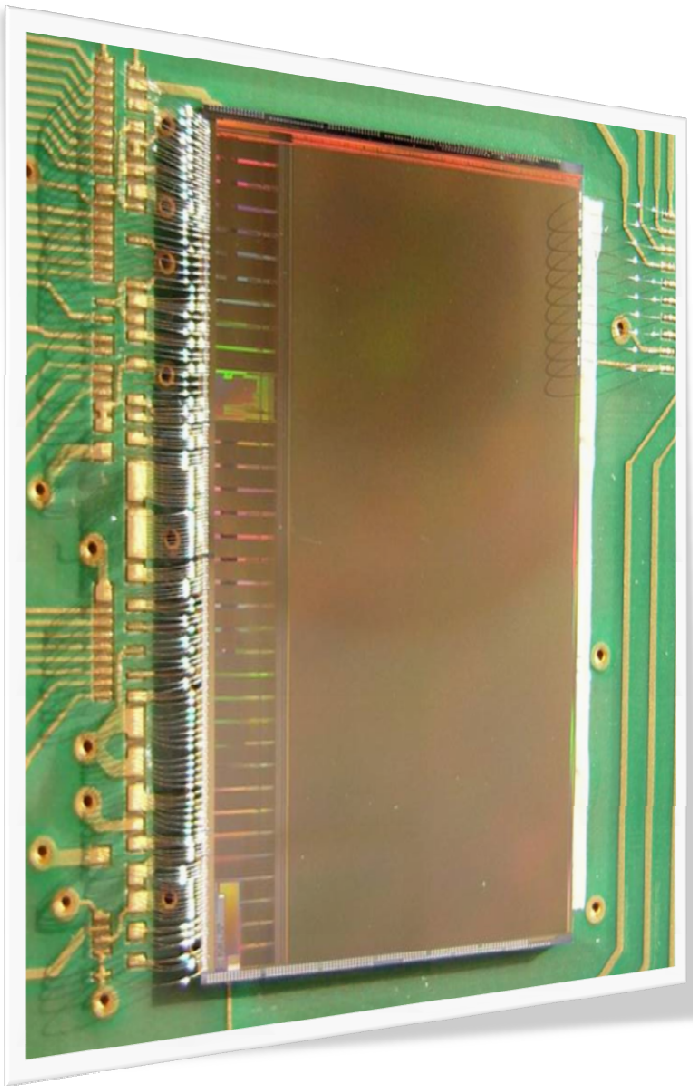
# Goals of the laboratory tests (done on IPHC test bench)

I r f u

cea

saclay

**IPHC**  
Institut Pluridisciplinaire  
Hubert Curie en  
STRASBOURG



## Analog test outputs :

- Temporal Noise (TN)
- Fixed Pattern Noise (FPN)
- Charge to Voltage Conversion Factor (CVF)
- Charge Collection Efficiency (CCE)  
for 3x3 and 5x5 Clusters

## Digital test outputs :

- Characterization of internal DACs
- TN and FPN for discriminators only
- TN and FPN for discriminators + pixels

## Working conditions :

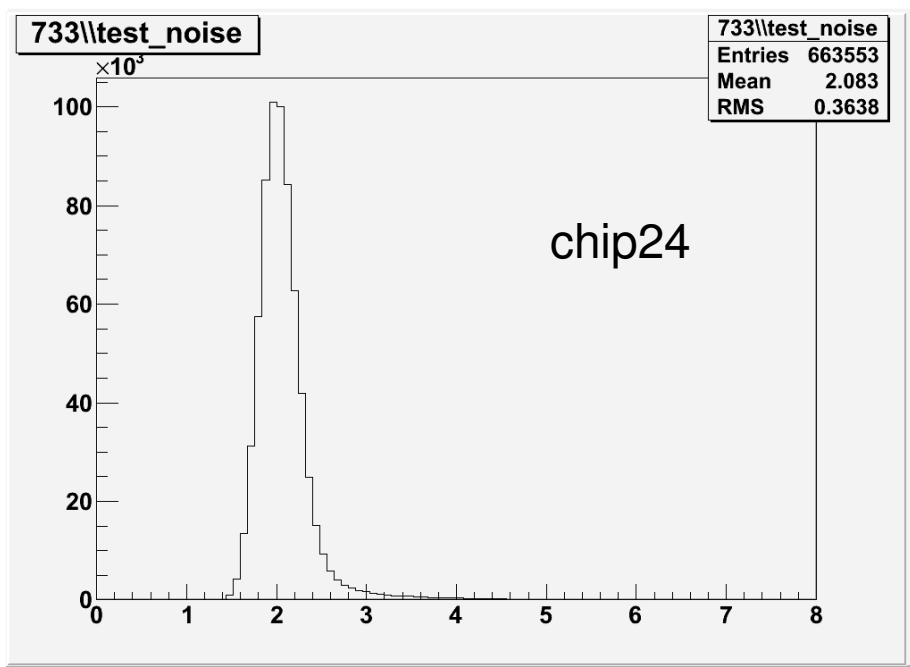
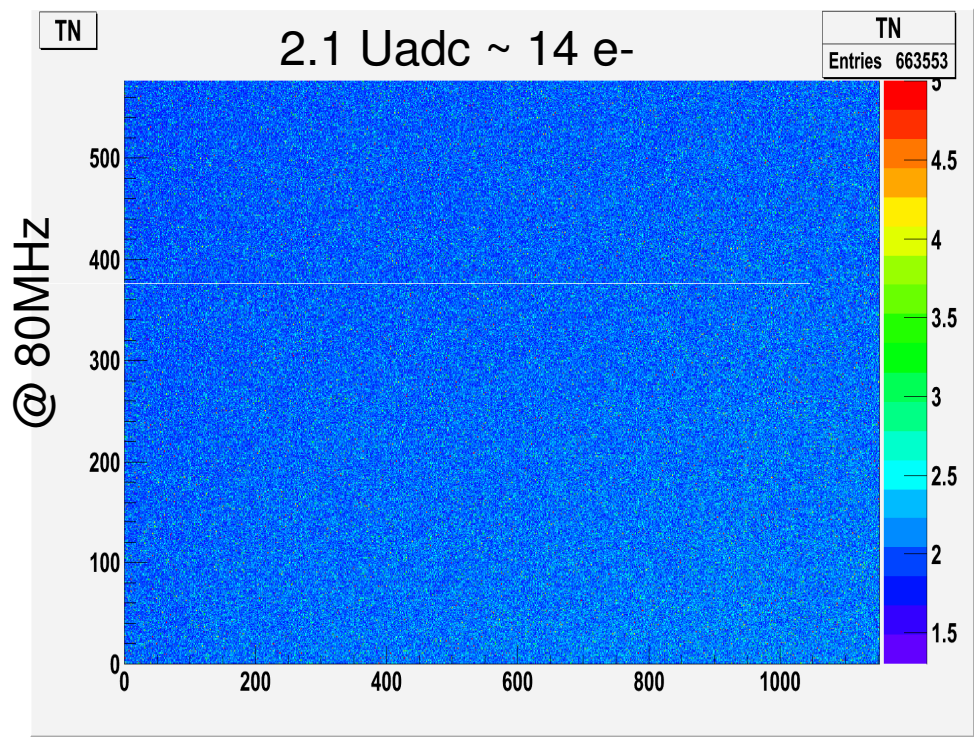
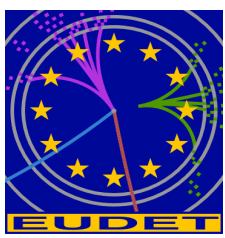
$$F_{\text{CLK-(chip)}} = 80\text{MHz} (\rightarrow 20\text{ MHz}) \Rightarrow T_{\text{integ}} = 112.5\ \mu\text{s} ; I_{\text{pix\_sf}} = 50\ \mu\text{A} ; T_{\text{chip}} \approx 20\ ^\circ\text{C}$$

# Results on analog test outputs

I r f u

cea  
saclay

IPHC  
Institut Pluridisciplinaire  
Hubert Curie en  
STRASBOURG



	Cluster size	Seed (1x1)	2x2	3x3	5x5
@ 20MHz	MIMOSA 26	22 %	55 %	73 %	83 %
	MIMOSA 22	22 %	58 %	75 %	86 %

TN  $\leq 14 e^-$  @80MHz, it decreases to  $\leq 12e^-$  @ 20MHz

# Results on digital test outputs

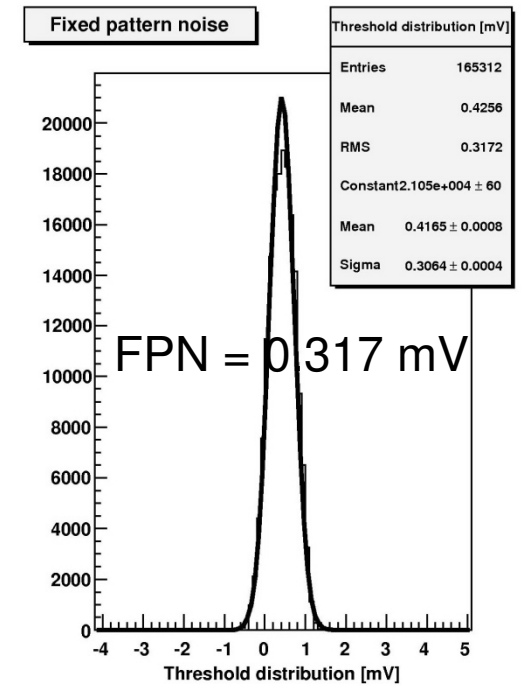
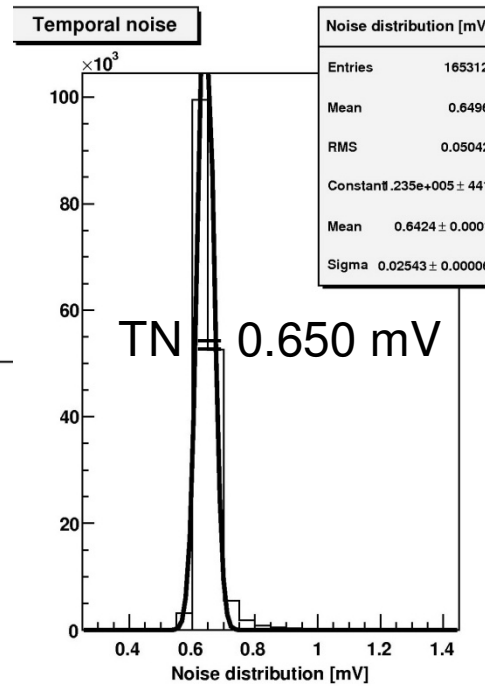
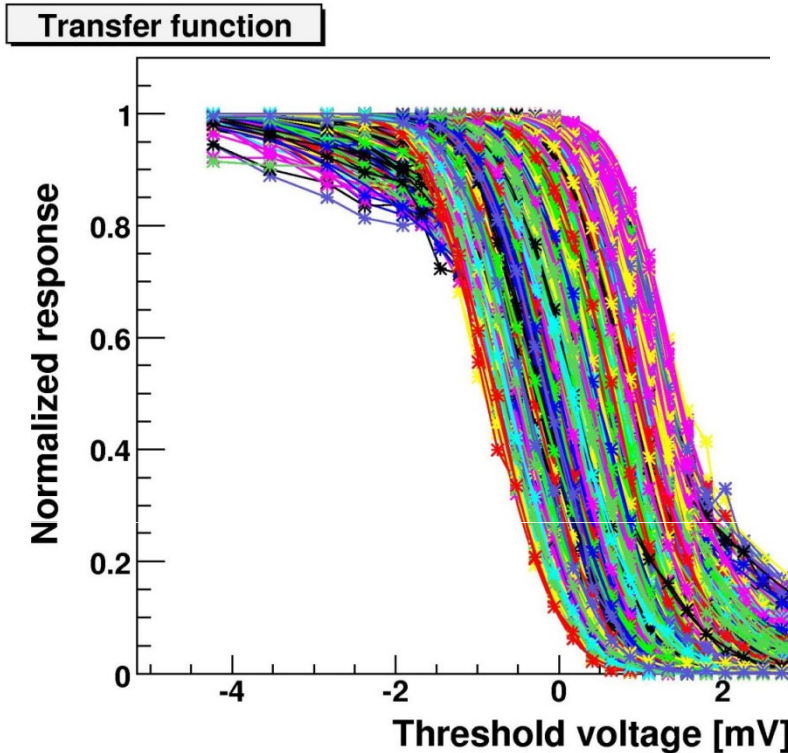
Group of 288 discriminators connected to pixels (165312 pixels)

I r f u

cea

saclay

IPHC  
Institut Pluridisciplinaire  
Hubert Curie en  
STRASBOURG

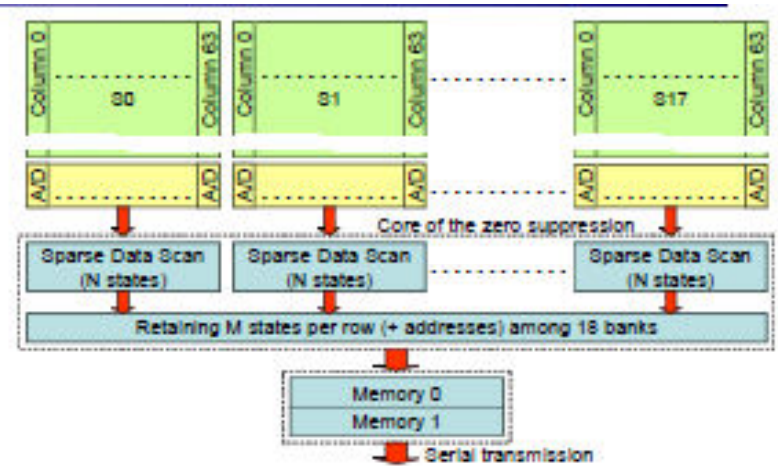


Chip6 - sub-array A

Noise values for the different groups and chips :

- TN ~ 0.6-0.7 mV
- FPN ~ 0.2-0.3 mV

# Zero suppression logic test



Zero suppression is based on row by row sparse data scan readout

Zero suppression logic has been extensively investigated  
( disconnected from the rest of the chip)

Various patterns were emulated with a pattern generator,  
running through the logic millions of time without any errors up to 115 MHz  
(1.44 times nominal frequency)

# Summary of lab-characterized Chips



Characterization of 2 different types of sensors :

- 1 wafer of « standard » sensors (23 characterized) → 7 for Ingrid + 1 for Angelo
- 1 wafer of 120 $\mu$ m thinned sensors (6 characterized)

34 chips tested

1 chip from each wafer doesn't work (2chips) → 32 chips working

29 chips completely characterized

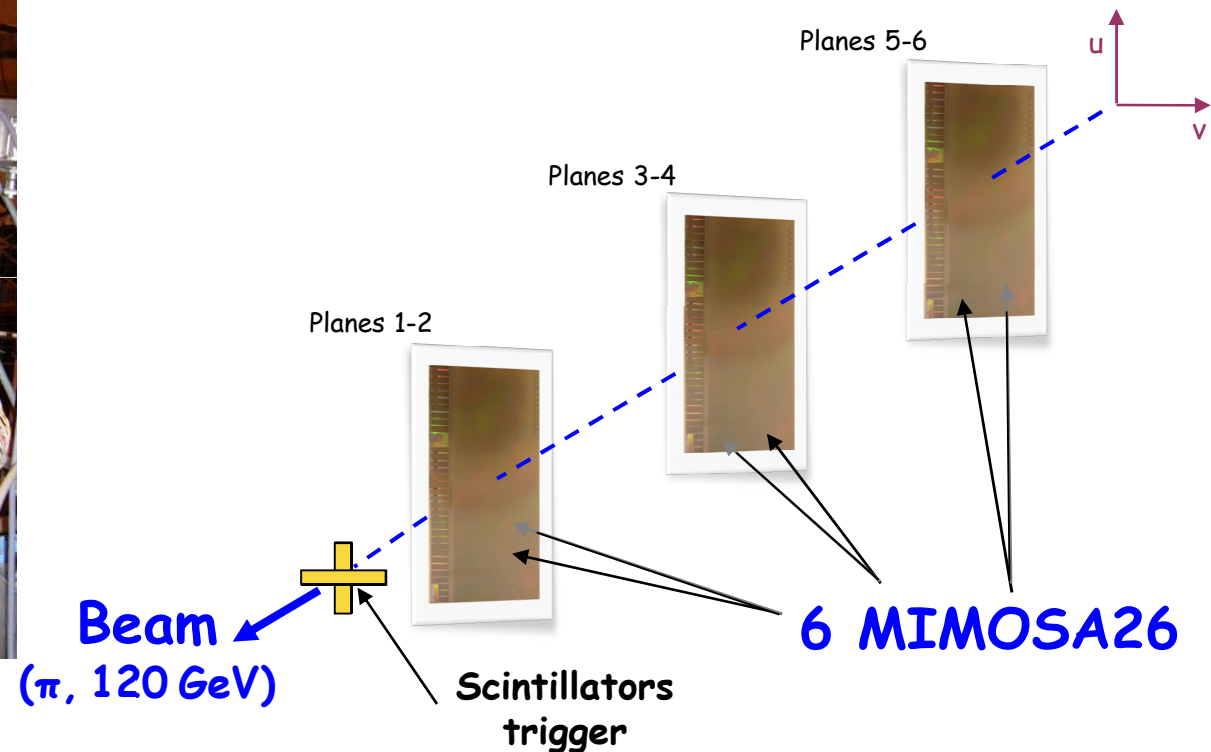
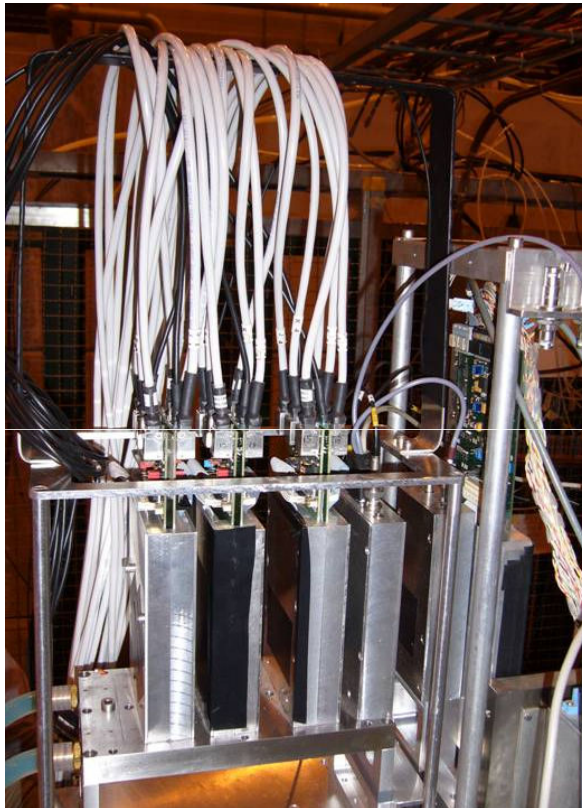
1 chip with 1 dead row and 1 dead column  
4 chips with 1 row or 1 column dead  
→ 24 chips fully working (77%) / 28 chips working correctly (>90%)



# Setup for the beam tests

A lot of measurements:

- 8 chips used : 2 standard, 6 120 $\mu$ m thinned
- 4 studied as DUT : 2 standard, 2 120 $\mu$ m thinned
- 54 runs taken, 25.10<sup>6</sup> events, 0.5To data

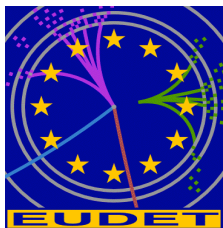


I r f u

cea

saclay

IPHC  
Institut Pluridisciplinaire  
Hubert Curie en  
STRASBOURG





# The different measurements

The different validation steps of the test beam:

1. ***validation of our setup***

→ 4 Runs with threshold from 14N to 6N

2. ***characterization of a 120 $\mu$ m thinned chip (chip24)***

→ 7 Runs with threshold from 12N to 4N

3. ***characterization of a unthinned chip (chip1)***

→ 9 Runs with 10N to 4.5N thresholds, 2 Vref2

4. ***DUT rotation***

→ 8 Runs at 0°, 45°, 58° (5N-8N threshold)

5. ***Homogeneity of all the array check***

→ 7 Runs by moving the beam or connected only 128 discri.

6. ***Characterization of 2 other chips as DUT***

One 120 $\mu$ m thinned chip (13) and one unthinned chip (4)

→ 4 Runs (3N-10N threshold)

7. ***Telescope check with different beam intensity***

→ 3 Runs (5,5k→1.3k)

8. ***Characterisation of chip1 & chip24 @ 20MHz***

→ 3 Runs (5N→8N)

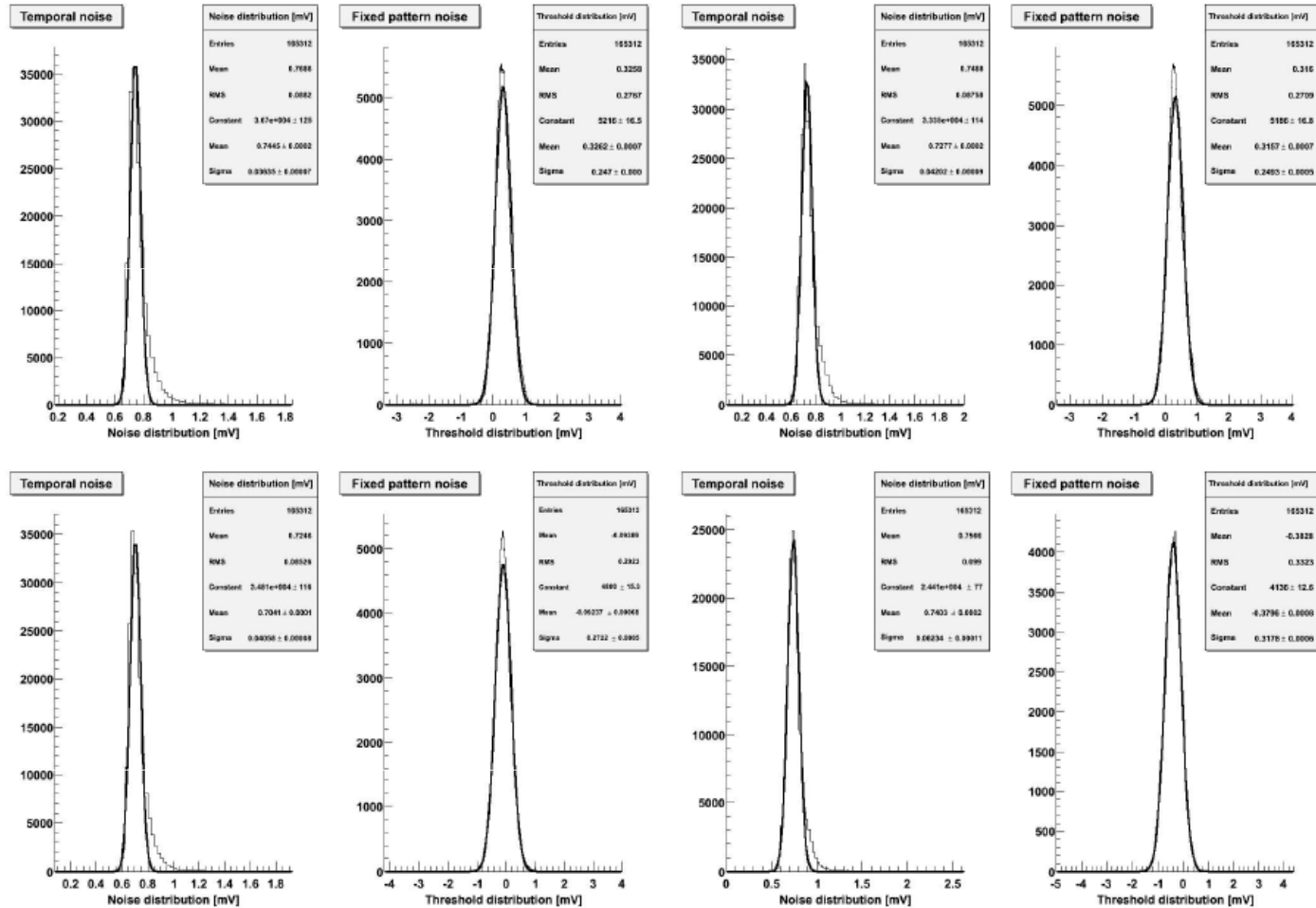
I r f u

cea

saclay



# Noise Study

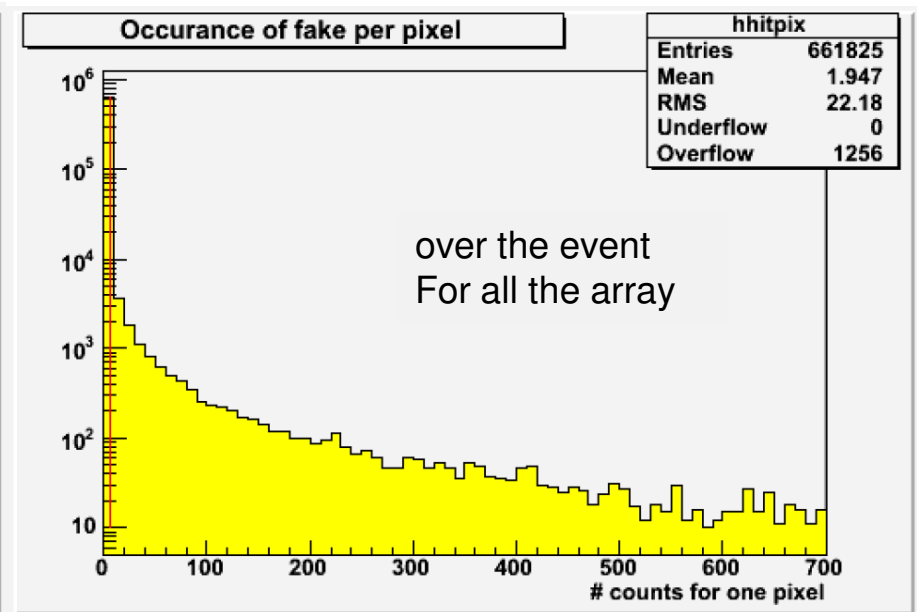
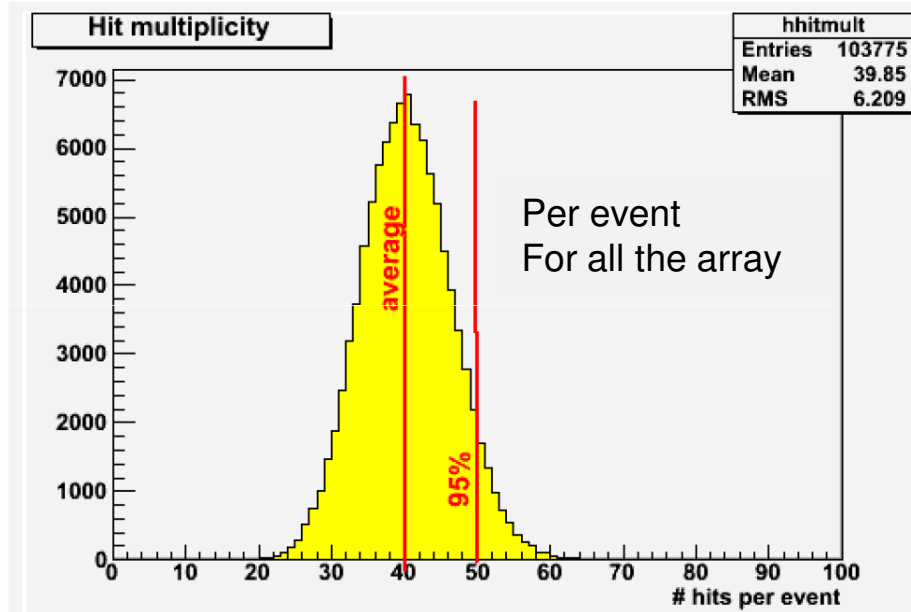


Noise:

- scan of discriminator thresholds performed  
→ Same results as in lab



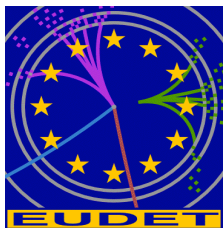
# Fake hit rate study



- 40 pixels touched /event at a 6N threshold  $\rightarrow 0.6 \cdot 10^{-4}$  rate
- Noise fluctuation : a few pixels are singing

Fake hit rate ( $10^{-4}$ /pixel/event):

Discri. threshold	5 N	6 N	7N	8 N	10 N	12 N
Chip24 (120 $\mu$ m thinned)	1.6	0.6	0.24	0.095	0.026	0.017
Chip1 (standard)	3.3	1.2	-	0.23	0.054	-



# ⊘ output performances with MIPs

I r f u

cea

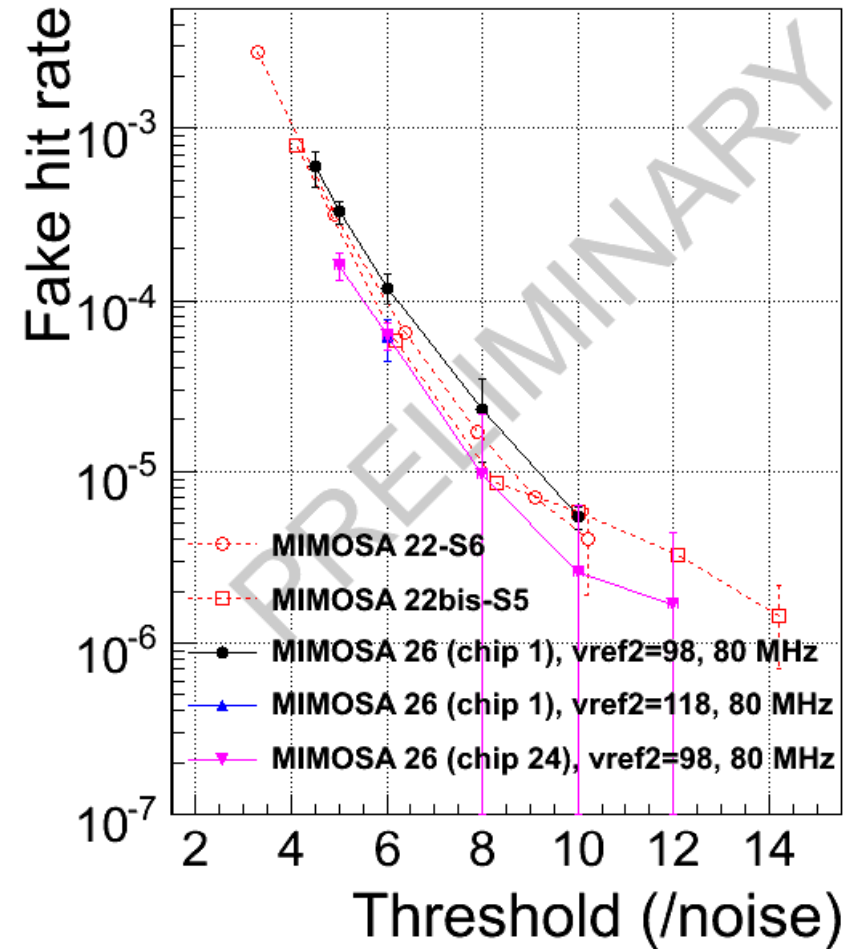
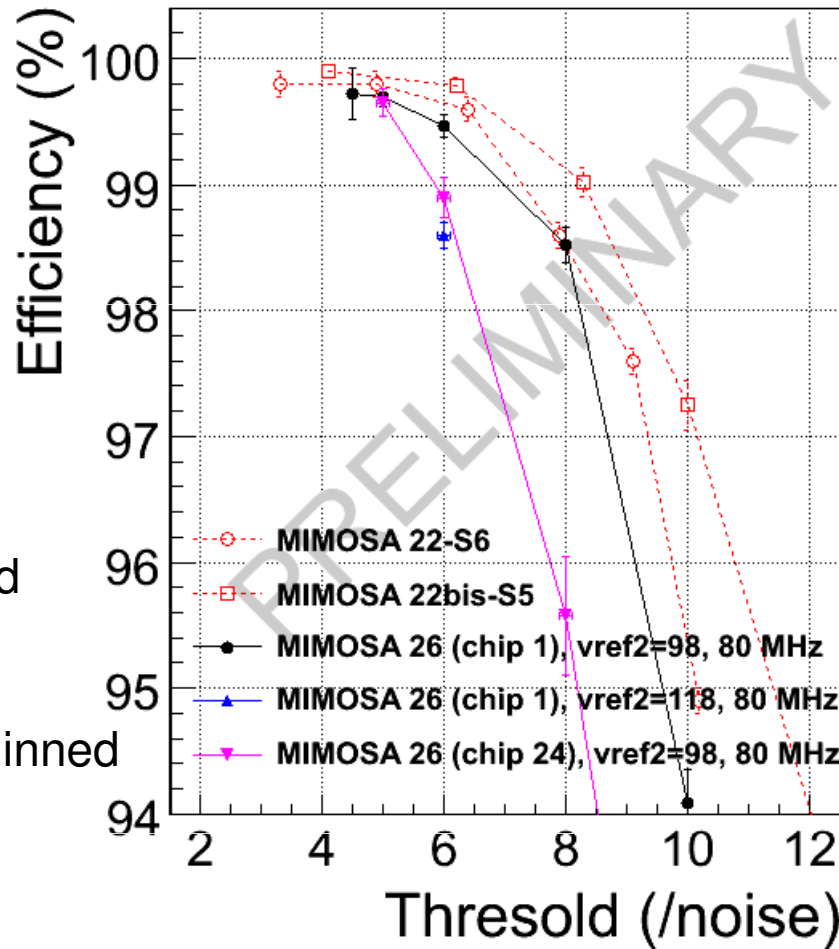
saclay

**Op:**

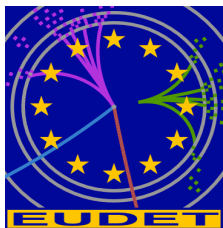
Unthinned

Chip24 :

120 $\mu$ m thinned



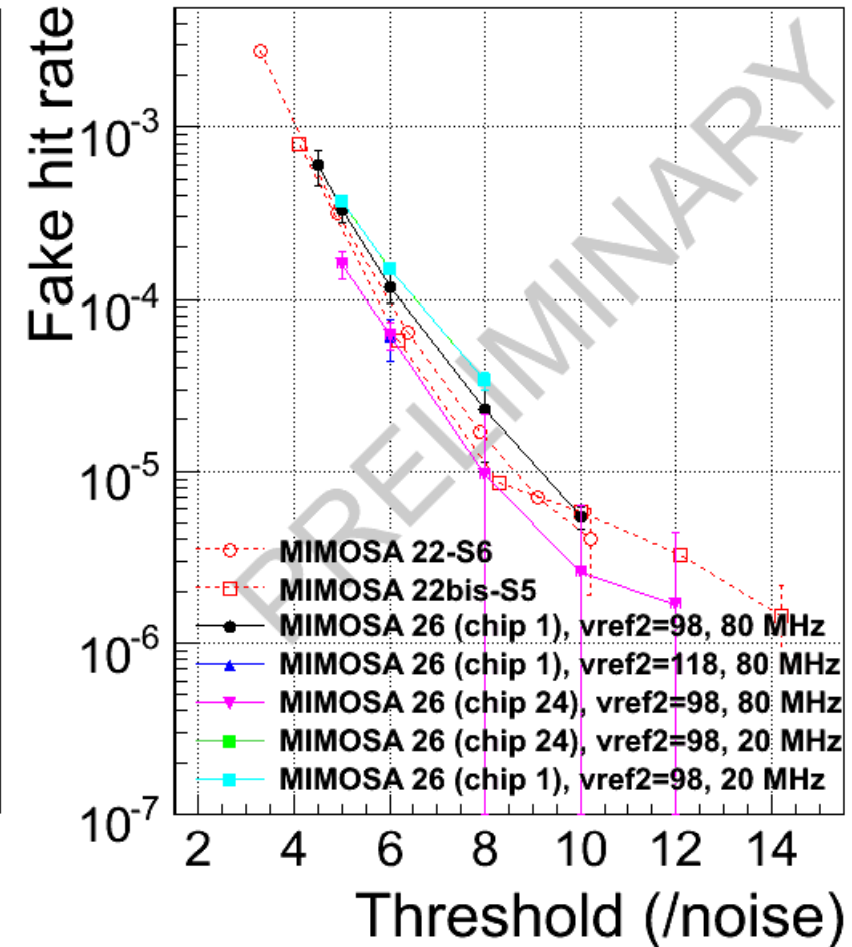
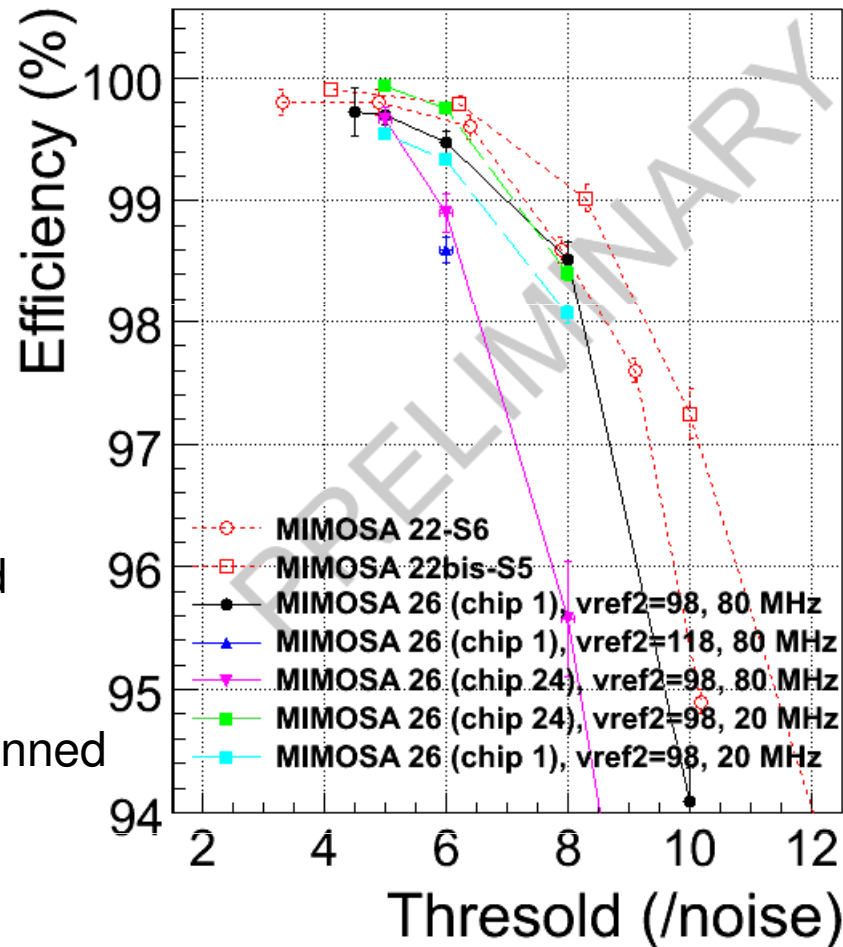
- det. eff.  $\sim 99.5 \pm 0.1$  % for a fake hit rate  $\sim 1 \cdot 10^{-4}$
- satisfactory performances for Mi26 (even if they are a little bit bellow one observed for Mi22/Mi22bis)
- resolution  $\sim 4.5 \mu\text{m}$  (Mi22  $\sim 4 \mu\text{m}$ )  $\rightarrow$  still in progress to be understood



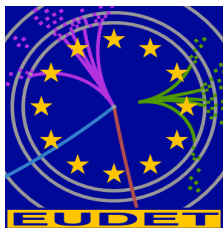
# ⊘ output performances with MIPs

**Op:**  
Unthinned

Chip24 :  
120 $\mu$ m thinned



- det. eff.  $\sim 99.5 \pm 0.1$  % for a fake hit rate  $\sim 1 \cdot 10^{-4}$
- satisfactory performances for Mi26  
(even if they are a little bit below one observed for Mi22/Mi22bis)
- resolution  $\sim 4.5 \mu\text{m}$  (Mi22  $\sim 4 \mu\text{m}$ )  $\rightarrow$  still in progress to be understood



# Cluster characteristics

Irfu

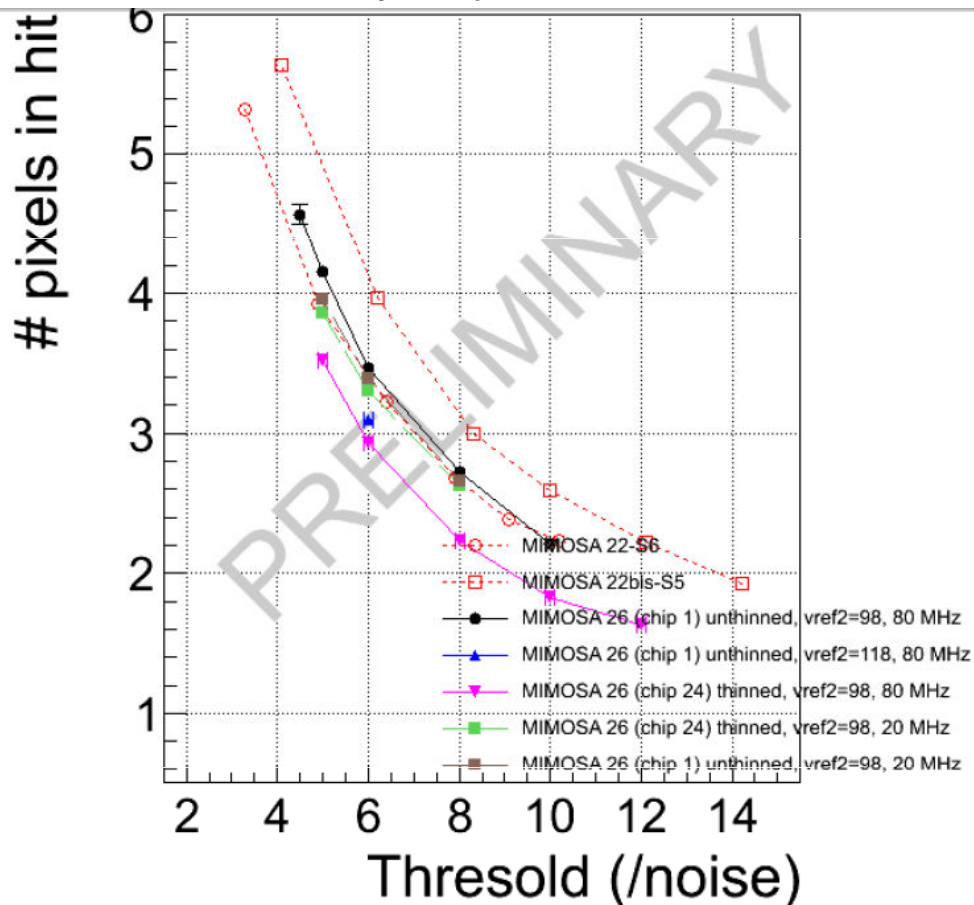
cea

saclay

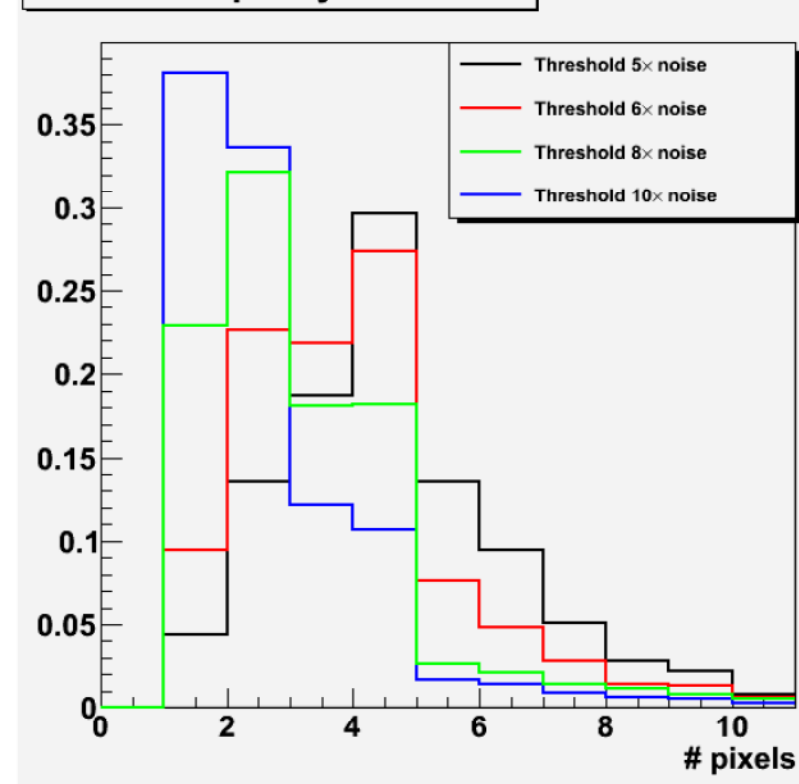
IPHC  
Institut Pluridisciplinaire  
Hubert Curie en  
STRASBOURG



Pixel multiplicity vs threshold



Pixel multiplicity in cluster



- similar tendency between the different MIMOSA22/22bis and MIMOSA26 chips
- for 6N cut -> 3.5 pixels hit in average, for 10% of the events just one pixel touched

# Summary

## Lab tests :

- MIMOSA26 is working properly compared to what is expected with MIMOSA22
- TN  $\sim$  0.6-0.7 mV – FPN  $\sim$  0.2-0.3 mV

## Beam tests :

- analysis still in progress:
  - improve the cluster position reconstruction
  - Study efficiency per sub-array
  - study “angle” run
- det. eff.  $\sim$  99.5  $\pm$  0.1 % for a fake hit rate  $\sim$   $1 \cdot 10^{-4}$
- resolution  $\sim$  4.5  $\mu$ m (Mi22  $\sim$  4  $\mu$ m)

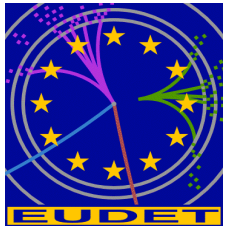
**$\Rightarrow$  Mi26 performances are efficient for EuDet telescope**

I r f u



saclay

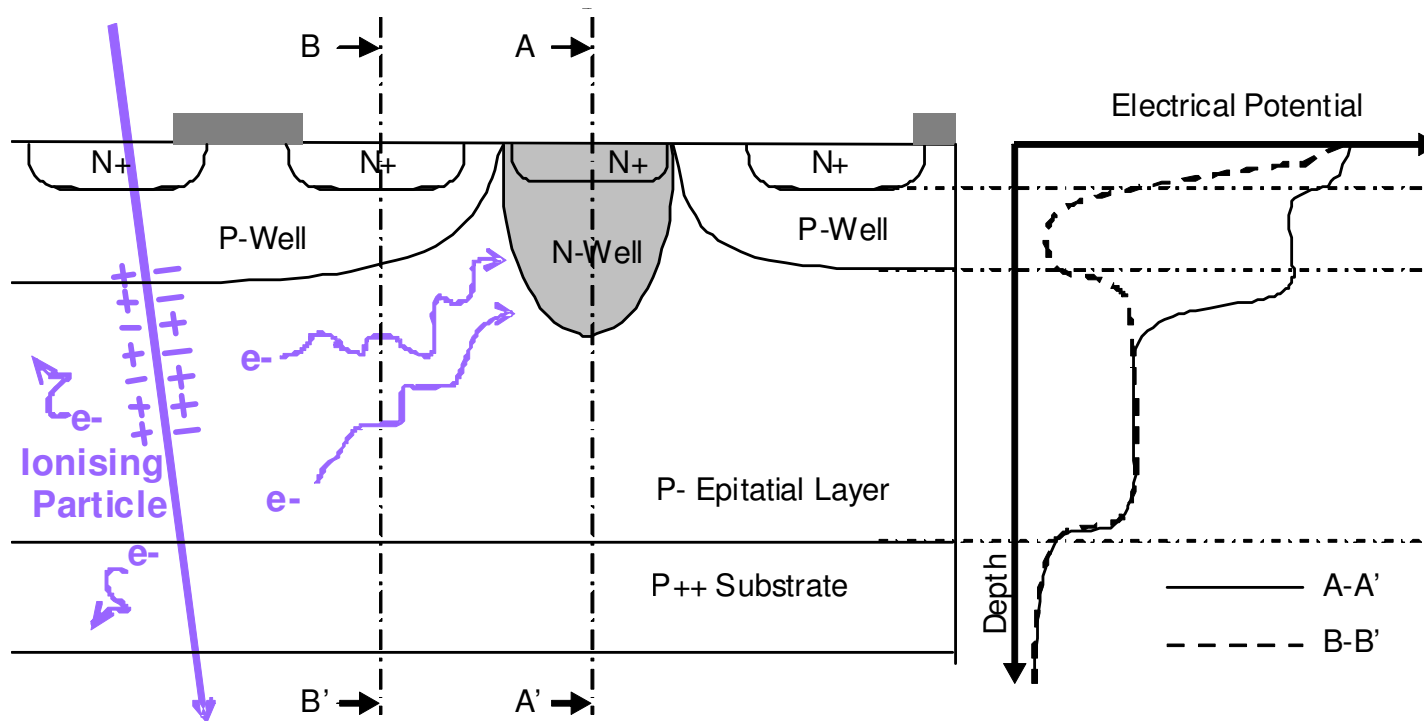
*Thank you for your attention*



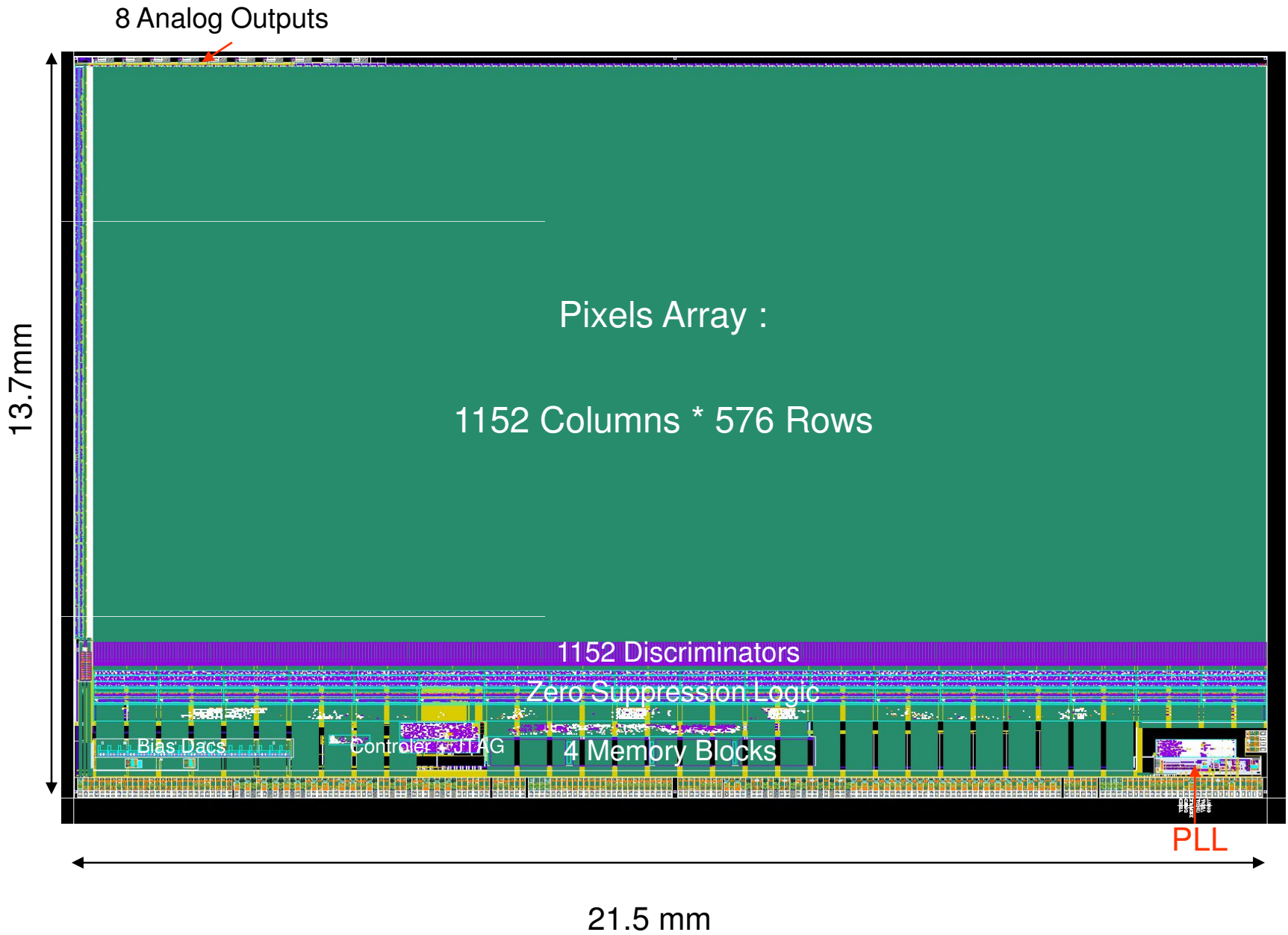


# MAPS (*Monolithic Active Pixel Sensor*) Principle

- sensing elements and processing electronics on the same substrate using a standard CMOS process
- Ionizing particles create e-h pairs in the lowly doped epi-layer
- electrons diffuse thermally to the N-well/P-Epi diode



**100% Fill Factor**  
80 e-h/ $\mu\text{m}$  (MIP)



# EUDET Testbeam Infrastructure (JRA1)

## (Detector R&D toward International Linear Collider)

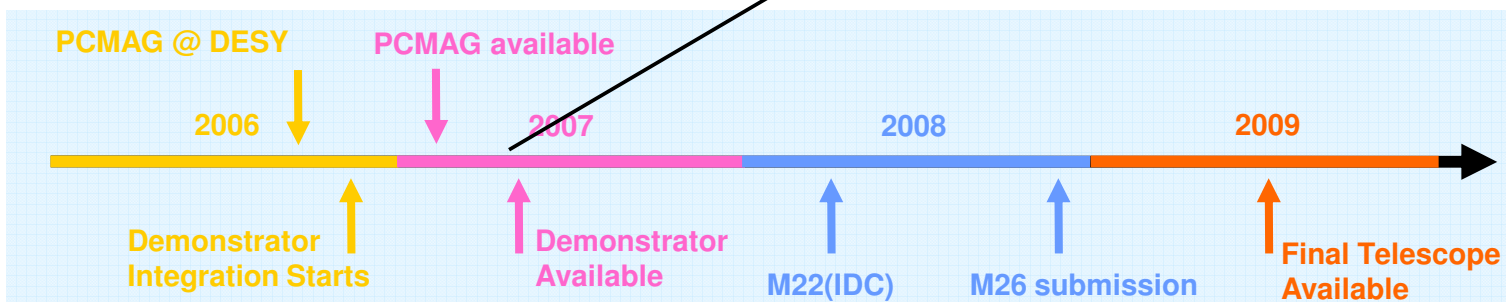
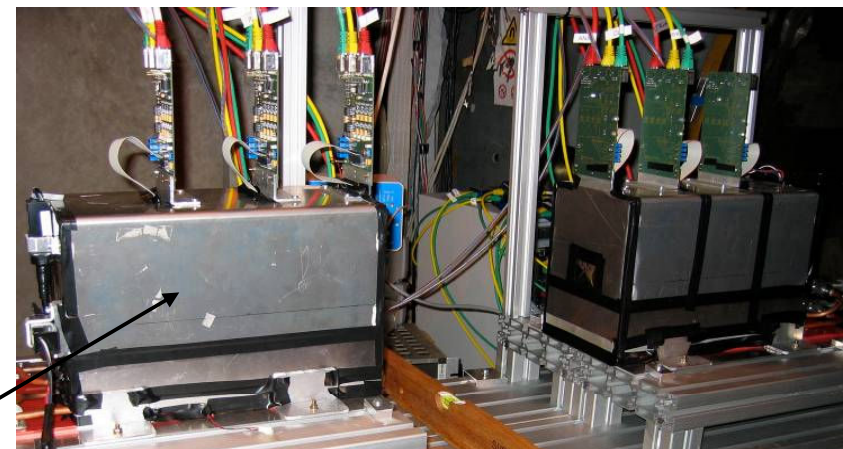
I r f u

cea

saclay

IPHC  
Institut Pluridisciplinaire  
Hubert Curie en  
STRASBOURG

- Provide a large high field magnet
- **Provide beam telescope with 6 layers of MAPS with :**
  - Very high precision ( < 3 $\mu$ m precision even at lower energies)
  - High readout speed ( frame rate > 1 kHz),  $T_{\text{integ time}} \sim 100\mu\text{s/frame}$
  - Binary readout
  - Easy to use (well defined/described interfaces)
  - Wide range of conditions for devices under test (cooling, positioning, magnetic field)
- **Major users :**  
Pixels, CCD and DEPFET detectors, TPC, ...
- Initial setup @ DESY  
< 6 GeV/c electrons
- Transportable :  
Hadron beams at FNAL, SLAC or CERN



# Summary of lab-characterized Chips

I r f u

cea

saclay

Characterization of 2 different types of sensors :

- 1 wafer of « standard » sensors (23 characterized)  
→ 7 for Ingrid + 1 for Angelo
- 1 wafer of 120 $\mu$ m thinned sensors (6 characterized)

1 chip from each wafer doesn't work (2chips)

1 chip with 1 dead row and 1 dead column

4 chips with 1 row or 1 column dead

